STL35N15F3

N-channel 150 V, 0.0355 Ω, 7 A STripFET™ III Power MOSFET in PowerFLAT™ 5x6 package

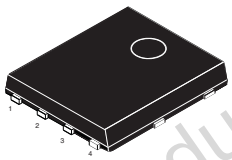
Datasheet — production data

Features

Order code	V_{DSS}	$R_{DS(on)}$ max	I_D
STL35N15F3	150 V	< 0.04 Ω	7 A (1)

1. The value is rated according $R_{thj\text{-}pcb}$

- Improved die-to-footprint ratio
- Very low profile package (1mm max)
- Very low thermal resistance
- Low on-resistance



PowerFLAT™ 5x6

Application

- Switching application

Description

This device is an N-channel enhancement mode Power MOSFET produced using STMicroelectronics' STripFET™ III technology, which is specifically designed to minimize on-resistance and gate charge to provide superior switching performance.

Figure 1. Internal schematic diagram

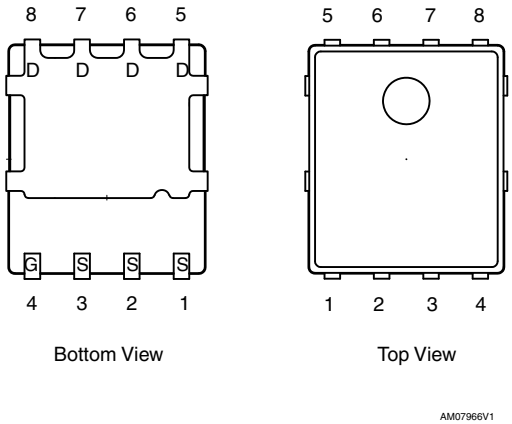


Table 1. Device summary

Order code	Marking	Package	Packaging
STL35N15F3	L35N15F3	PowerFLAT™ 5x6	Tape and reel

Obsolete Product(s) - Obsolete Product(s)

This is information on a product in full production. www.st.com

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Obsolete Product(s) - Obsolete Product(s)

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	150	V
V_{GS}	Gate-source voltage	± 20	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	33	A
I_D (2)	Drain current (continuous) at T_{pcb} = 25 °C	7	A
I_D (2)	Drain current (continuous) at T_{pcb} = 100 °C	4.3	A
I_{DM} (3),(2)	Drain current (pulsed)	28	A
P_{TOT} (1)	Total dissipation at T_C = 25 °C	80	W
P_{TOT} (2)	Total dissipation at T_{pcb} = 25 °C	4	W
T_J T_{stg}	Operating junction temperature Storage temperature	-55 to 150	°C

1. The value is rated according to $R_{thj\text{-}c}$
2. The value is rated according to $R_{thj\text{-}pcb}$
3. Pulse width limited by safe operating area

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	1.56	°C/W
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	31.3	°C/W

1. When mounted on FR-4 board of 1inch², 2oz Cu, t < 10 sec

Obsolete Product(s) - Obsolete Product(s)

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS}= 0	150			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 150 V V_{DS} = 150 V, T_C = 125 °C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ±20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250 µA	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS}= 10 V, I_D= 3.5 A		0.0355	0.04	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} =25 V, f=1 MHz, V_{GS}=0	-	1905 171 28	-	pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD}=15 V, I_D = 6 A V_{GS} =10 V *Figure 14*	-	49.4 7.3 22.6	-	nC nC nC
R_G	Gate input resistance	f=1 MHz Gate DC Bias = 0 Test signal level = 20 mV open drain	-	1.7	-	Ω

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD}=75 V, I_D= 3.5 A, R_G= 4.7 Ω, V_{GS}=10 V *Figure 13*	-	14 11 57 20	-	ns ns ns ns

Obsolete Product(s) - Obsolete Product(s)

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		7	A
I_{SDM}(1)	Source-drain current (pulsed)		-		28	A
V_{SD}(2)	Forward on voltage	I_{SD}= 6 A, V_{GS}=0	-		1.3	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD}= 6 A, di/dt = 100 A/µs, V_{DD}=120 V, Tj=150 °C	-	124 670 11		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300µs, duty cycle 1.5%

Obsolete Product(s) - Obsolete Product(s)

2.1 Electrical characteristics

Figure 2. Safe operating area

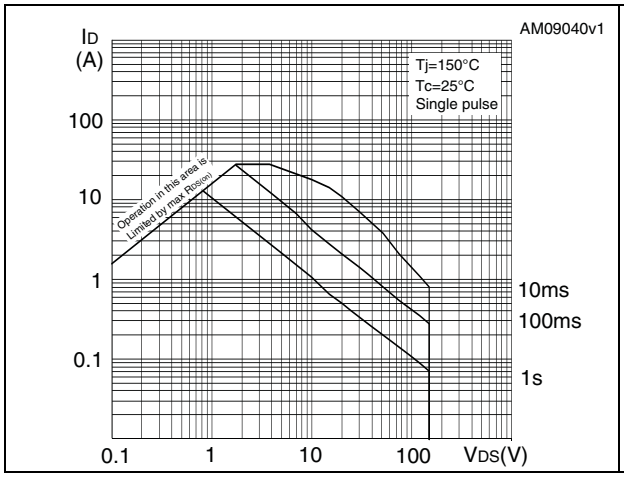


Figure 3. Thermal impedance

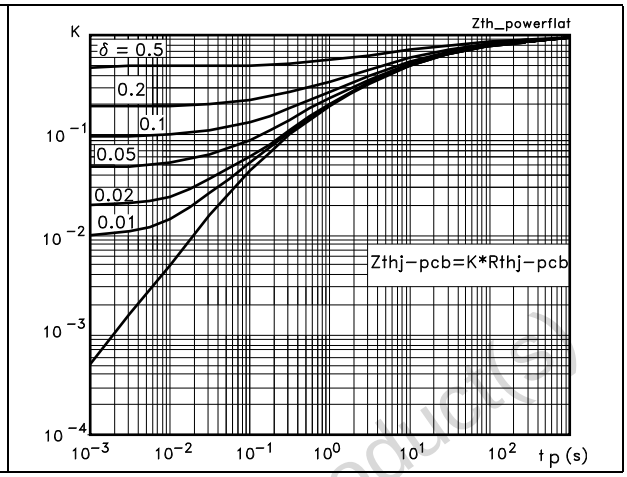


Figure 4. Output characteristics

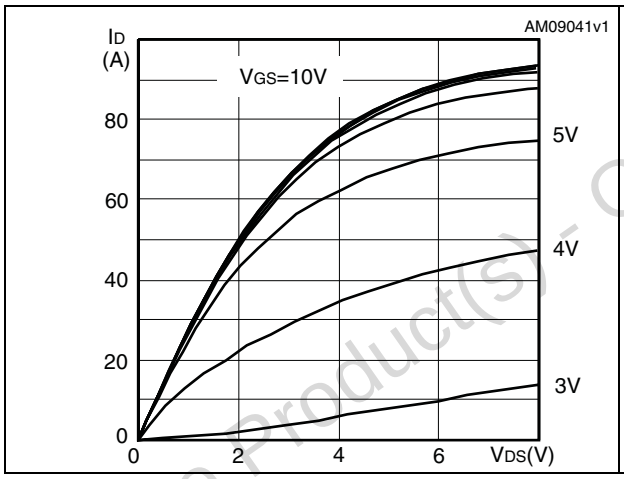


Figure 5. Transfer characteristics

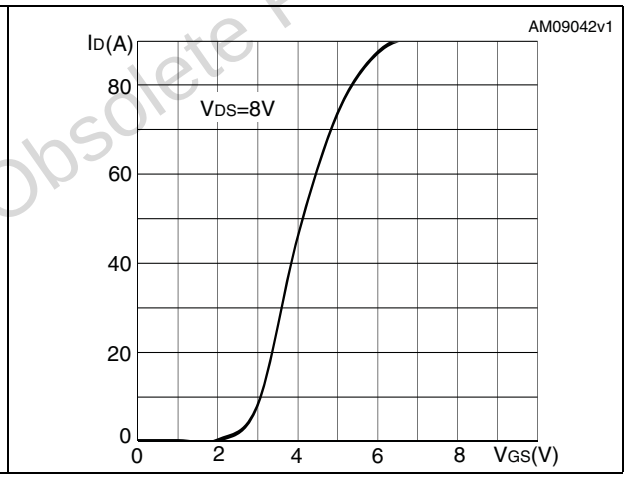


Figure 6. Normalized B_{VDSS} vs temperature

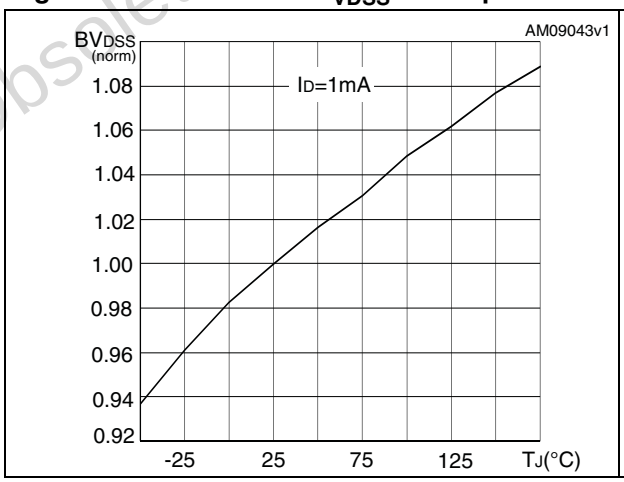
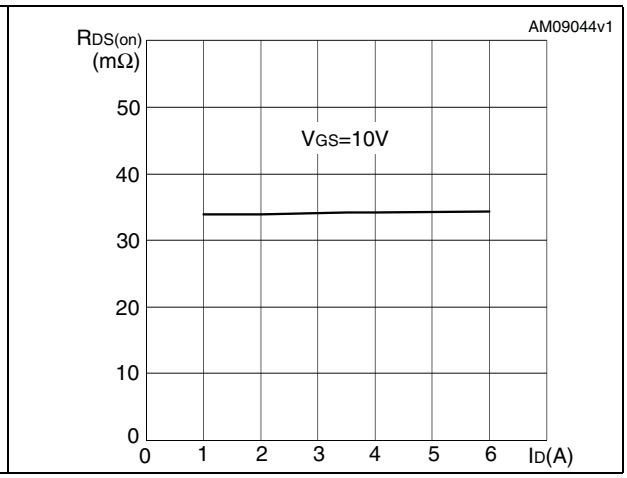


Figure 7. Static drain-source on-resistance



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Figure 8. Gate charge vs gate-source voltage

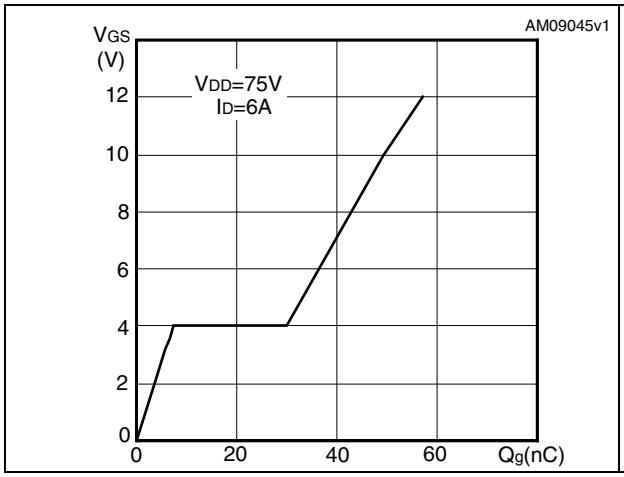


Figure 9. Capacitance variations

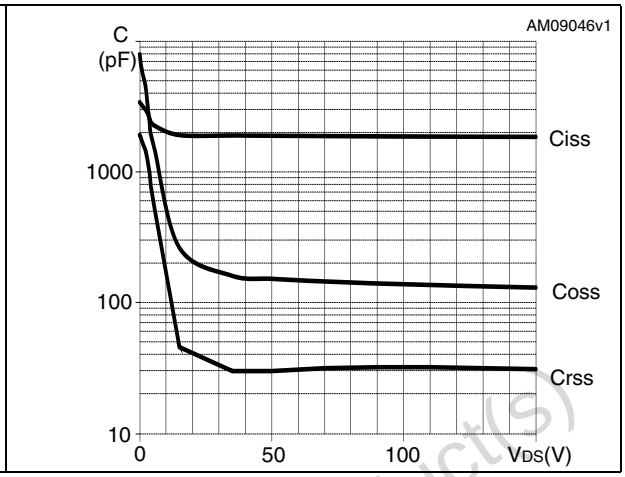


Figure 10. Normalized gate threshold voltage vs temperature

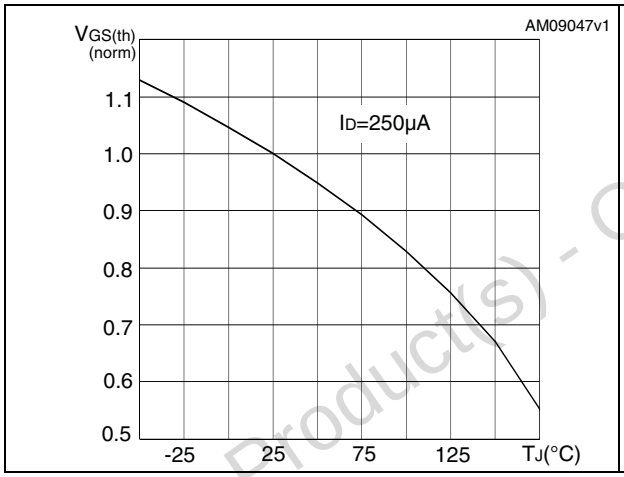


Figure 11. Normalized on-resistance vs temperature

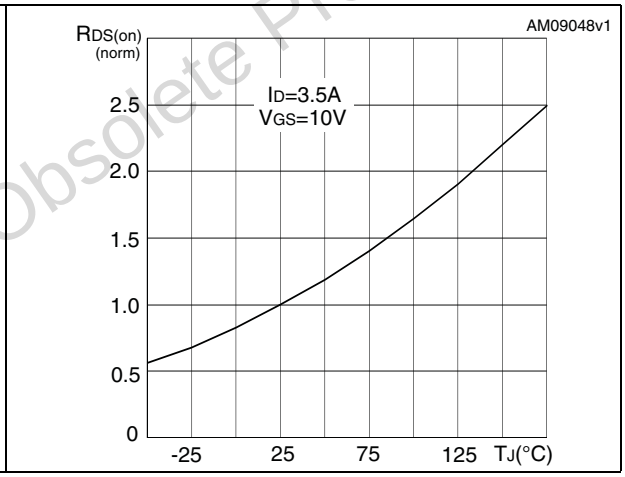
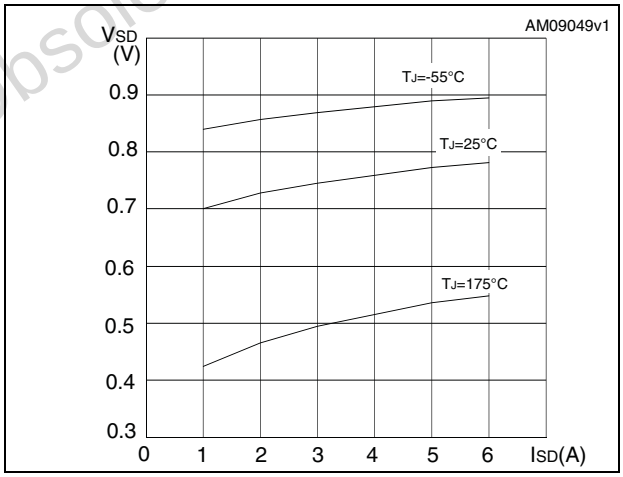


Figure 12. Source-drain diode forward characteristics



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3 Test circuits

Figure 13. Switching times test circuit for resistive load

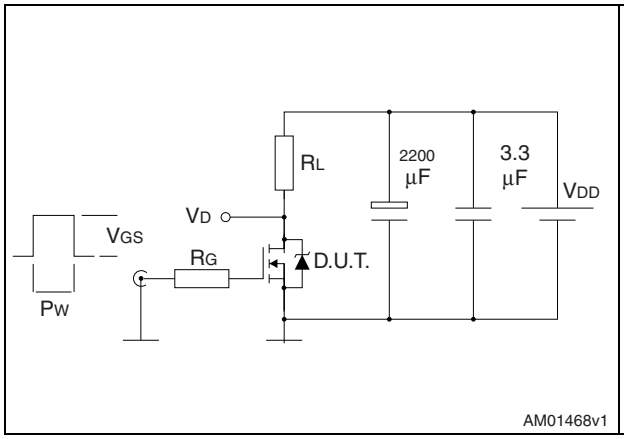


Figure 14. Gate charge test circuit

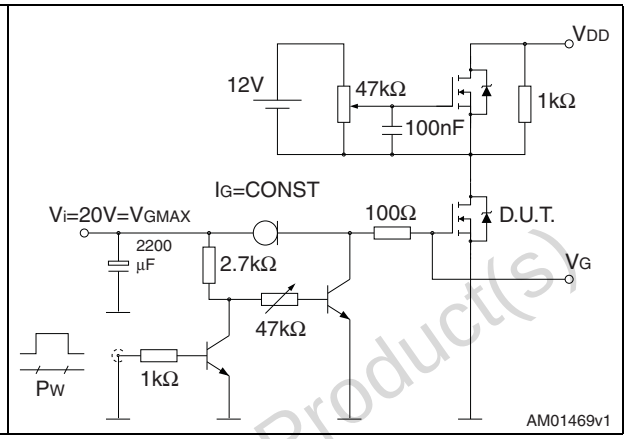


Figure 15. Test circuit for inductive load switching and diode recovery times

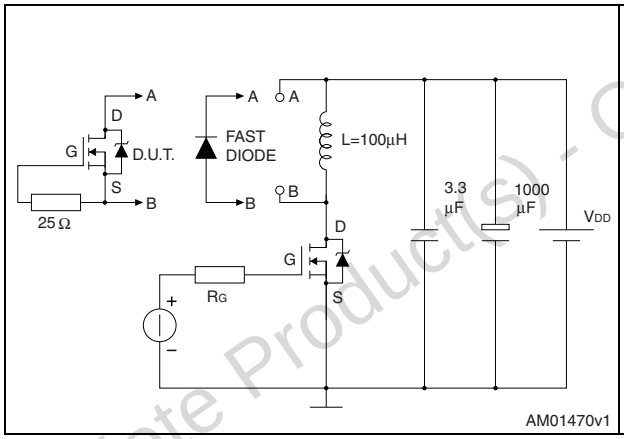


Figure 16. Unclamped inductive load test circuit

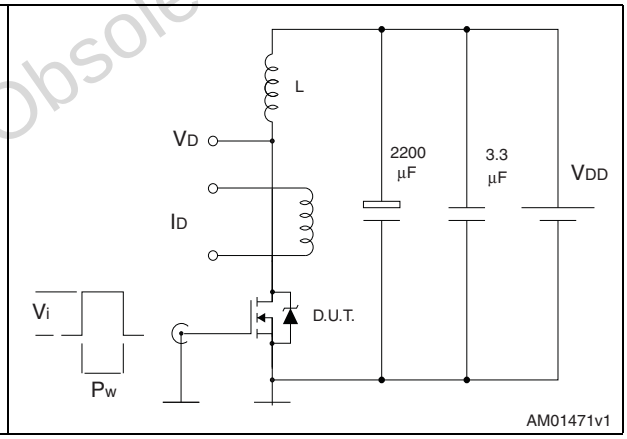


Figure 17. Unclamped inductive waveform

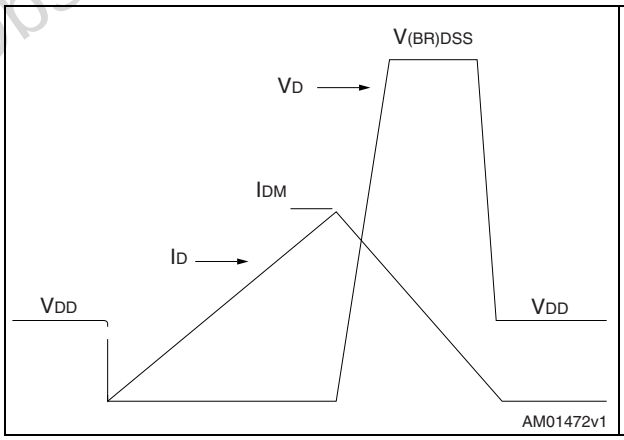
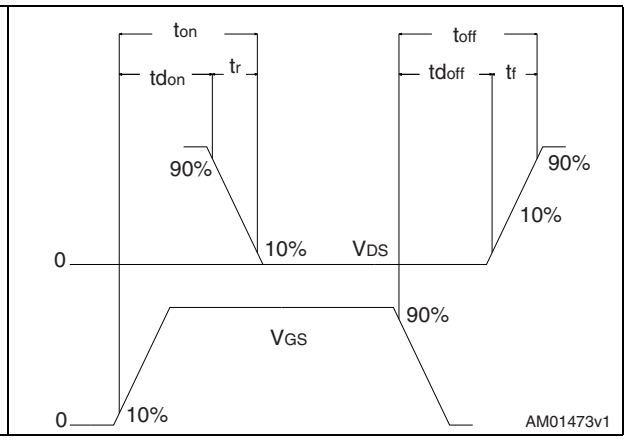


Figure 18. Switching time waveform



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4 Package mechanical data

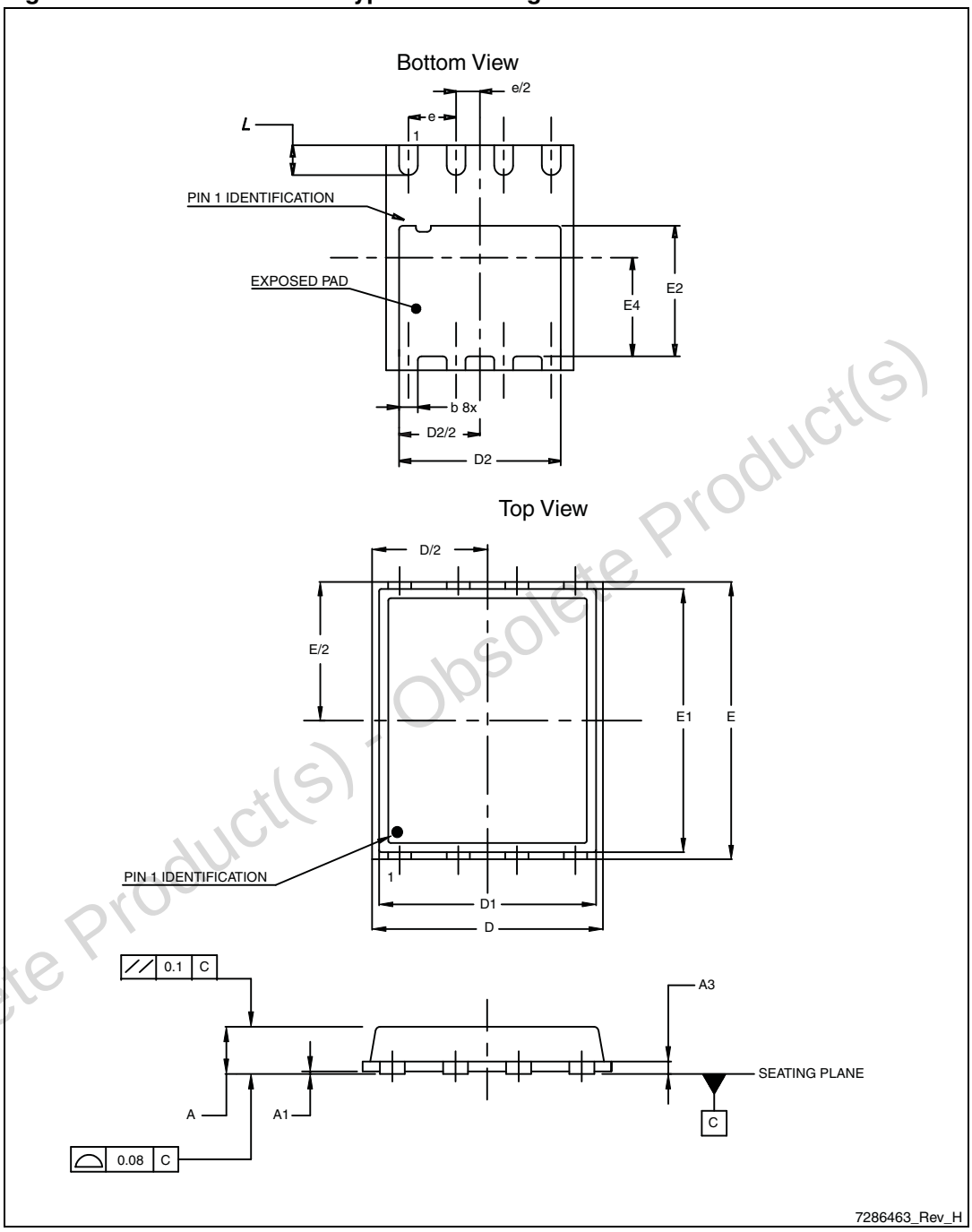
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Table 8. PowerFLAT™ 5x6 type C-B mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80	0.83	0.93
A1	0	0.02	0.05
A3		0.20	
b	0.35	0.40	0.47
D		5.00	
D1		4.75	
D2	4.15	4.20	4.25
E		6.00	
E1		5.75	
E2	3.43	3.48	3.53
E4	2.58	2.63	2.68
e		1.27	
L	0.70	0.80	0.90

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Figure 19. PowerFLAT™ 5x6 type C-B drawing



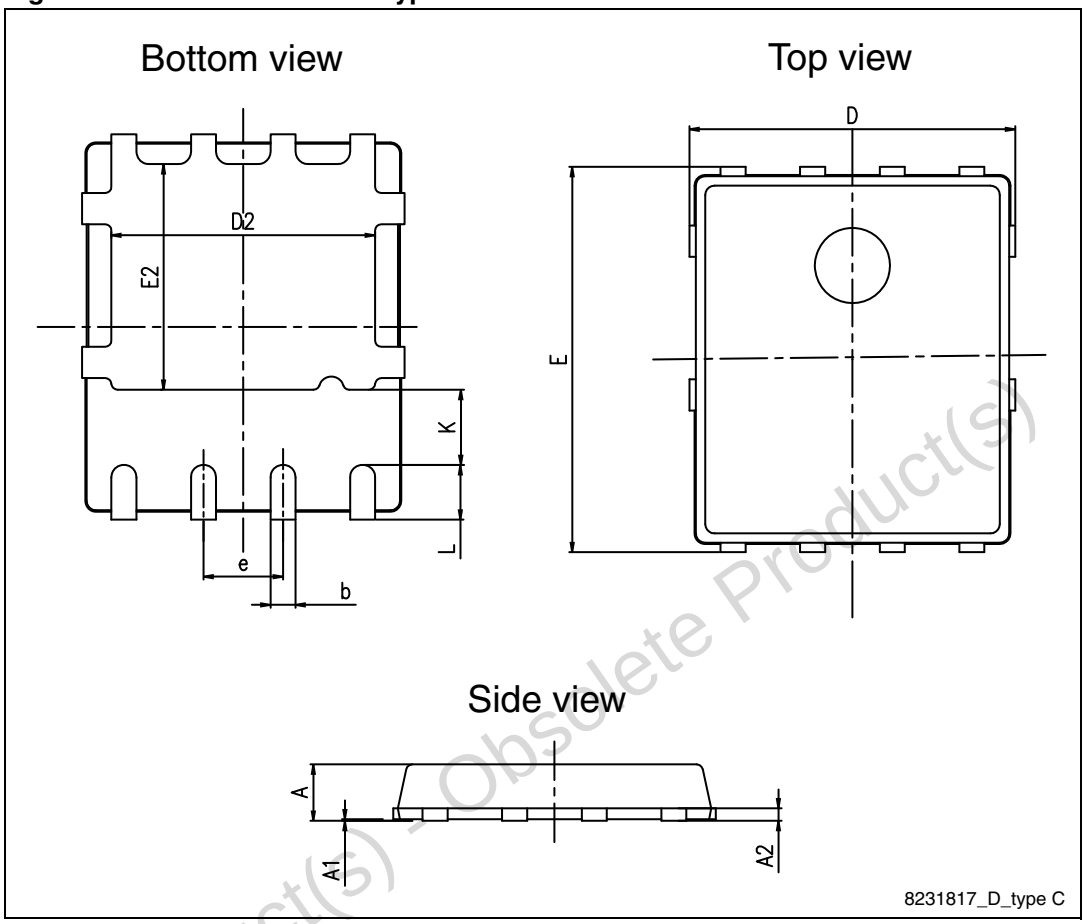
Obsolete Product(s) - Obsolete Product(s)

Table 9. PowerFLAT™ 5x6 type S-C mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
D		5.20	
E		6.15	
D2	4.11		4.31
E2	3.50		3.70
e		1.27	
e1		0.65	
L	0.715		1.015
K	1.05		1.35

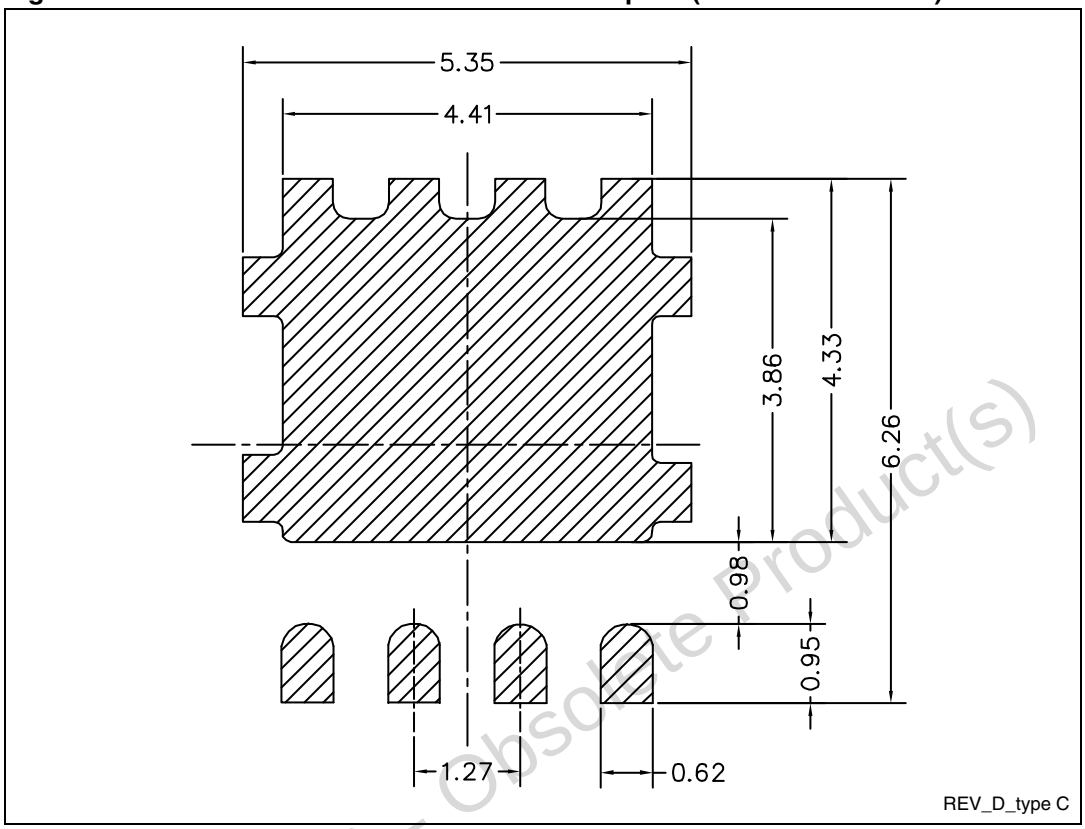
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Figure 20. PowerFLAT™ 5x6 type S-C mechanical data



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Figure 21. PowerFLAT™ 5x6 recommended footprint (dimensions in mm)



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5 Packaging mechanical data

Figure 22. PowerFLAT™ 5x6 tape

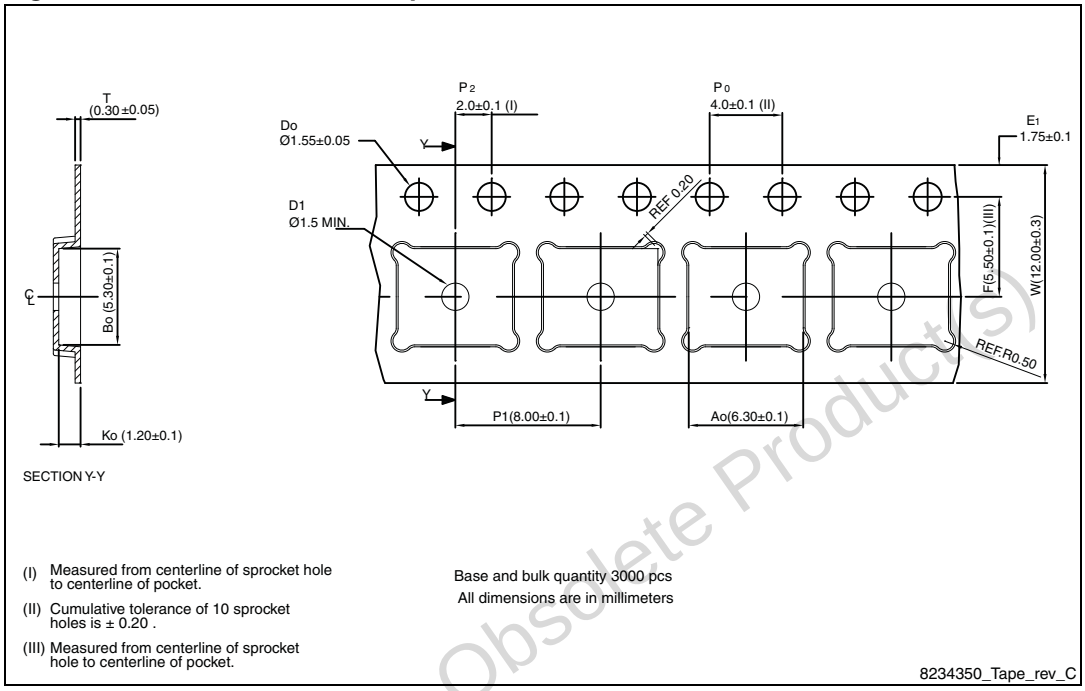
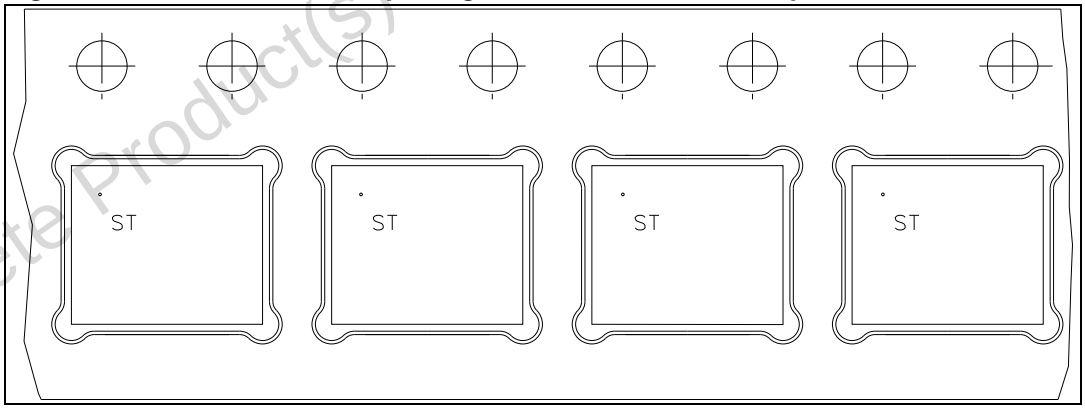
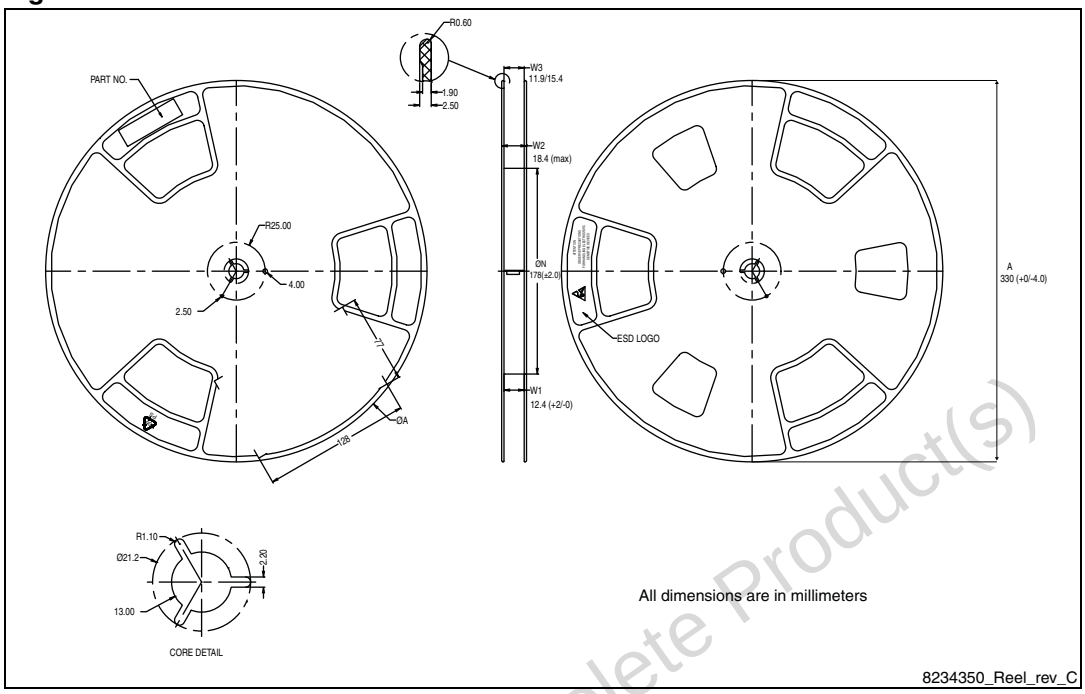


Figure 23. PowerFLAT™ 5x6 package orientation in carrier tape.



Obsolete Product(s) - Obsolete Product(s)

Figure 24. PowerFLAT™ 5x6 reel



Obsolete Product(s) - Obsolete Product(s)

6 Revision history

Table 10. Document revision history

Date	Revision	Changes
16-Mar-2011	1	Initial release.
10-May-2012	2	*Section 4: Package mechanical data* has been added. Minor text changes.

Obsolete Product(s) - Obsolete Product(s)

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